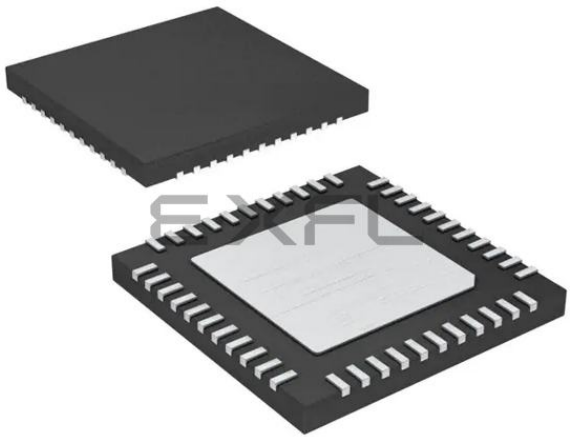
Microchip Technology - PIC32MX270F256DT-50I/ML Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	50MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	33
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx270f256dt-50i-ml

1.0 DEVICE OVERVIEW

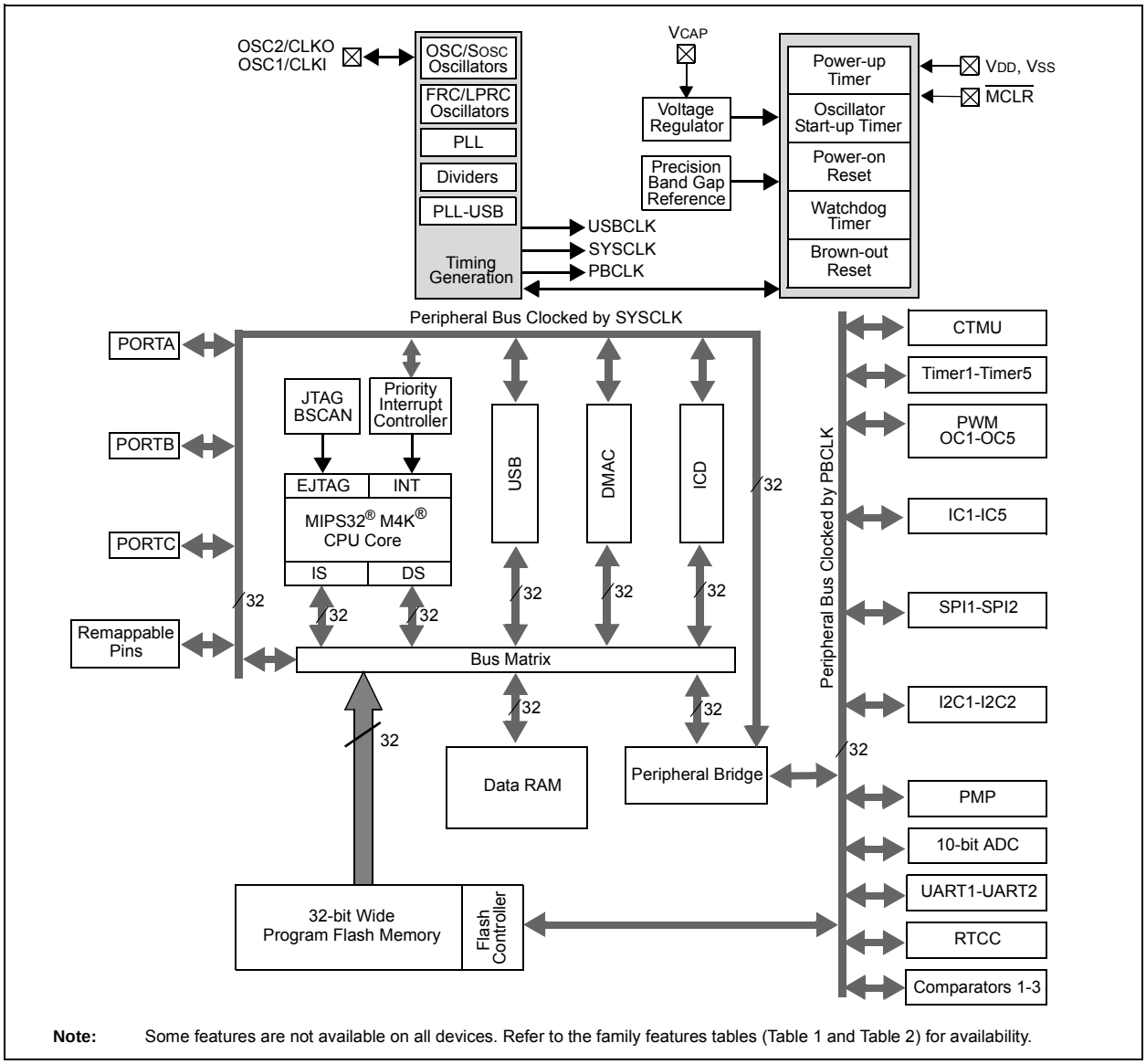
Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to documents listed in the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

This document contains device-specific information for PIC32MX1XX/2XX 28/36/44-pin Family devices.

Figure 1-1 illustrates a general block diagram of the core and peripheral modules in the PIC32MX1XX/2XX 28/36/44-pin Family of devices.

Table 1-1 lists the functions of the various pins shown in the pinout diagrams.

FIGURE 1-1: BLOCK DIAGRAM



Note: Some features are not available on all devices. Refer to the family features tables (Table 1 and Table 2) for availability.

2.8.1 CRYSTAL OSCILLATOR DESIGN CONSIDERATION

The following example assumptions are used to calculate the Primary Oscillator loading capacitor values:

- CIN = PIC32_OSC2_Pin Capacitance = ~4-5 pF
- COUT = PIC32_OSC1_Pin Capacitance = ~4-5 pF
- C1 and C2 = XTAL manufacturing recommended loading capacitance
- Estimated PCB stray capacitance, (i.e.,12 mm length) = 2.5 pF

EXAMPLE 2-1: CRYSTAL LOAD CAPACITOR CALCULATION

Crystal manufacturer recommended: $C1 = C2 = 15\ pF$

Therefore:

$$C_{LOAD} = \{([C_{IN} + C1] * [C_{OUT} + C2]) / [C_{IN} + C1 + C2 + C_{OUT}] \} + \text{estimated oscillator PCB stray capacitance}$$
$$= \{([5 + 15][5 + 15]) / [5 + 15 + 15 + 5] \} + 2.5\ pF$$
$$= \{([20][20]) / [40] \} + 2.5$$
$$= 10 + 2.5 = 12.5\ pF$$

Rounded to the nearest standard value or 12 pF in this example for Primary Oscillator crystals "C1" and "C2".

The following tips are used to increase oscillator gain, (i.e., to increase peak-to-peak oscillator signal):

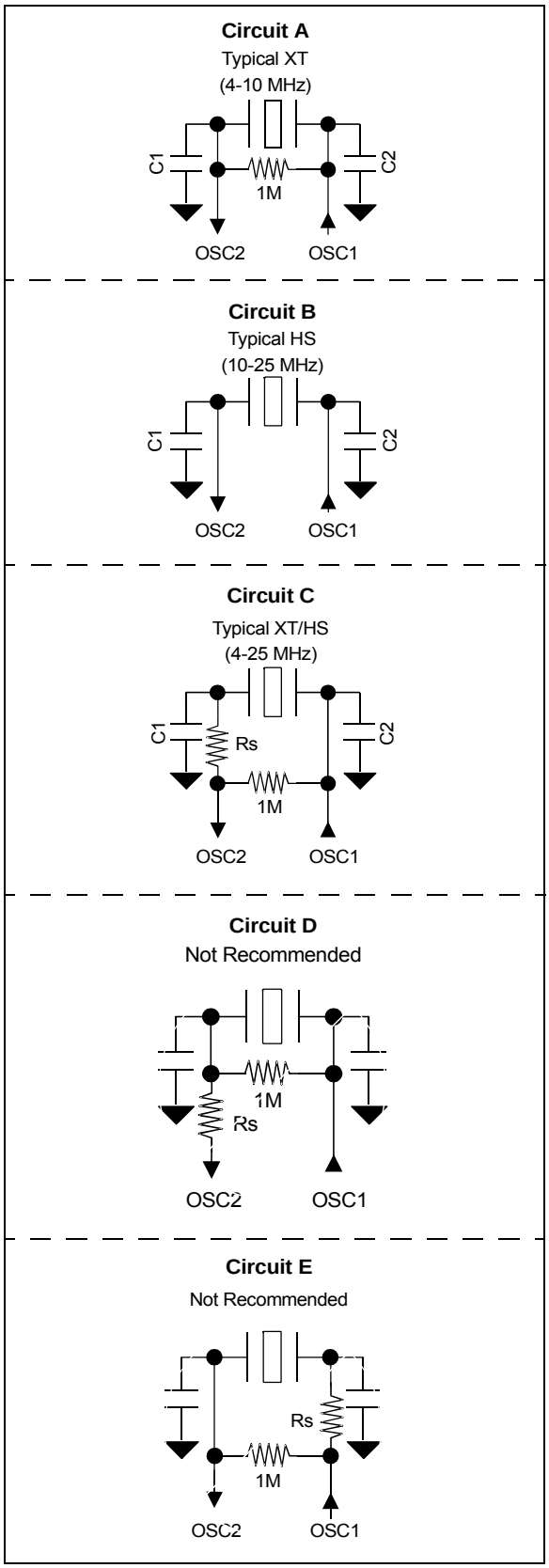
- Select a crystal with a lower "minimum" power drive rating
- Select an crystal oscillator with a lower XTAL manufacturing "ESR" rating.
- Add a parallel resistor across the crystal. The smaller the resistor value the greater the gain. It is recommended to stay in the range of 600k to 1M
- C1 and C2 values also affect the gain of the oscillator. The lower the values, the higher the gain.
- C2/C1 ratio also affects gain. To increase the gain, make C1 slightly smaller than C2, which will also help start-up performance.

Note: Do not add excessive gain such that the oscillator signal is clipped, flat on top of the sine wave. If so, you need to reduce the gain or add a series resistor, RS, as shown in circuit "C" in Figure 2-4. Failure to do so will stress and age the crystal, which can result in an early failure. Adjust the gain to trim the max peak-to-peak to ~VDD-0.6V. When measuring the oscillator signal you must use a FET scope probe or a probe with ≤ 1.5 pF or the scope probe itself will unduly change the gain and peak-to-peak levels.

2.8.1.1 Additional Microchip References

- AN588 *"PICmicro® Microcontroller Oscillator Design Guide"*
- AN826 *"Crystal Oscillator Basics and Crystal Selection for rfPIC™ and PICmicro® Devices"*
- AN849 *"Basic PICmicro® Oscillator Design"*

FIGURE 2-4: PRIMARY CRYSTAL OSCILLATOR CIRCUIT RECOMMENDATIONS



REGISTER 5-1: NVMCON: PROGRAMMING CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R-0	R-0	R-0	U-0	U-0	U-0
	WR	WREN	WRERR(1)	LVDERR(1)	LVDSTAT(1)	—	—	—
7:0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	—	—	NVMOP<3:0>			

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **WR:** Write Control bit

This bit is writable when WREN = 1 and the unlock sequence is followed.

1 = Initiate a Flash operation. Hardware clears this bit when the operation completes
0 = Flash operation is complete or inactive

bit 14 **WREN:** Write Enable bit

This is the only bit in this register reset by a device Reset.

1 = Enable writes to WR bit and enables LVD circuit
0 = Disable writes to WR bit and disables LVD circuit

bit 13 **WRERR:** Write Error bit(1)

This bit is read-only and is automatically set by hardware.

1 = Program or erase sequence did not complete successfully
0 = Program or erase sequence completed normally

bit 12 **LVDERR:** Low-Voltage Detect Error bit (LVD circuit must be enabled)(1)

This bit is read-only and is automatically set by hardware.

1 = Low-voltage detected (possible data corruption, if WRERR is set)
0 = Voltage level is acceptable for programming

bit 11 **LVDSTAT:** Low-Voltage Detect Status bit (LVD circuit must be enabled)(1)

This bit is read-only and is automatically set and cleared by the hardware.

1 = Low-voltage event is active
0 = Low-voltage event is not active

bit 10-4 **Unimplemented:** Read as '0'

bit 3-0 **NVMOP<3:0>:** NVM Operation bits

These bits are writable when WREN = 0.

1111 = Reserved
•
•
•
0111 = Reserved
0110 = No operation
0101 = Program Flash Memory (PFM) erase operation: erases PFM, if all pages are not write-protected
0100 = Page erase operation: erases page selected by NVMADDR, if it is not write-protected
0011 = Row program operation: programs row selected by NVMADDR, if it is not write-protected
0010 = No operation
0001 = Word program operation: programs word selected by NVMADDR, if it is not write-protected
0000 = No operation

Note 1: This bit is cleared by setting NVMOP == 'b0000, and initiating a Flash operation (i.e., WR).

7.1 Interrupt Control Registers

TABLE 7-2: INTERRUPT REGISTER MAP

Virtual Address (BF88_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
1000	INTCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	MVEC	—	TPC<2:0>			—	—	—	INT4EP	INT3EP	INT2EP	INT1EP	INT0EP	0000
1010	INTSTAT(3)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	SRIPL<2:0>			—	—	VEC<5:0>						0000
1020	IPTMR	31:16	IPTMR<31:0>																0000
		15:0																	0000
1030	IFS0	31:16	FCEIF	RTCCIF	FSCMIF	AD1IF	OC5IF	IC5IF	IC5EIF	T5IF	INT4IF	OC4IF	IC4IF	IC4EIF	T4IF	INT3IF	OC3IF	IC3IF	0000
		15:0	IC3EIF	T3IF	INT2IF	OC2IF	IC2IF	IC2EIF	T2IF	INT1IF	OC1IF	IC1IF	IC1EIF	T1IF	INT0IF	CS1IF	CS0IF	CTIF	0000
1040	IFS1	31:16	DMA3IF	DMA2IF	DMA1IF	DMA0IF	CTMUIF	I2C2MIF	I2C2SIF	I2C2BIF	U2TXIF	U2RXIF	U2EIF	SPI2TXIF	SPI2RXIF	SPI2EIF	PMPEIF	PMPIF	0000
		15:0	CNCIF	CNBIF	CNAIF	I2C1MIF	I2C1SIF	I2C1BIF	U1TXIF	U1RXIF	U1EIF	SPI1TXIF	SPI1RXIF	SPI1EIF	USBIF(2)	CMP3IF	CMP2IF	CMP1IF	0000
1060	IEC0	31:16	FCEIE	RTCCIE	FSCMIE	AD1IE	OC5IE	IC5IE	IC5EIE	T5IE	INT4IE	OC4IE	IC4IE	IC4EIE	T4IE	INT3IE	OC3IE	IC3IE	0000
		15:0	IC3EIE	T3IE	INT2IE	OC2IE	IC2IE	IC2EIE	T2IE	INT1IE	OC1IE	IC1IE	IC1EIE	T1IE	INT0IE	CS1IE	CS0IE	CTIE	0000
1070	IEC1	31:16	DMA3IE	DMA2IE	DMA1IE	DMA0IE	CTMUIE	I2C2MIE	I2C2SIE	I2C2BIE	U2TXIE	U2RXIE	U2EIE	SPI2TXIE	SPI2RXIE	SPI2EIE	PMPEIE	PMPIE	0000
		15:0	CNCIE	CNBIE	CNAIE	I2C1MIE	I2C1SIE	I2C1BIE	U1TXIE	U1RXIE	U1EIE	SPI1TXIE	SPI1RXIE	SPI1EIE	USBIE(2)	CMP3IE	CMP2IE	CMP1IE	0000
1090	IPC0	31:16	—	—	—	INT0IP<2:0>			INT0IS<1:0>		—	—	—	CS1IP<2:0>			CS1IS<1:0>		0000
		15:0	—	—	—	CS0IP<2:0>			CS0IS<1:0>		—	—	—	CTIP<2:0>			CTIS<1:0>		0000
10A0	IPC1	31:16	—	—	—	INT1IP<2:0>			INT1IS<1:0>		—	—	—	OC1IP<2:0>			OC1IS<1:0>		0000
		15:0	—	—	—	IC1IP<2:0>			IC1IS<1:0>		—	—	—	T1IP<2:0>			T1IS<1:0>		0000
10B0	IPC2	31:16	—	—	—	INT2IP<2:0>			INT2IS<1:0>		—	—	—	OC2IP<2:0>			OC2IS<1:0>		0000
		15:0	—	—	—	IC2IP<2:0>			IC2IS<1:0>		—	—	—	T2IP<2:0>			T2IS<1:0>		0000
10C0	IPC3	31:16	—	—	—	INT3IP<2:0>			INT3IS<1:0>		—	—	—	OC3IP<2:0>			OC3IS<1:0>		0000
		15:0	—	—	—	IC3IP<2:0>			IC3IS<1:0>		—	—	—	T3IP<2:0>			T3IS<1:0>		0000
10D0	IPC4	31:16	—	—	—	INT4IP<2:0>			INT4IS<1:0>		—	—	—	OC4IP<2:0>			OC4IS<1:0>		0000
		15:0	—	—	—	IC4IP<2:0>			IC4IS<1:0>		—	—	—	T4IP<2:0>			T4IS<1:0>		0000
10E0	IPC5	31:16	—	—	—	AD1IP<2:0>			AD1IS<1:0>		—	—	—	OC5IP<2:0>			OC5IS<1:0>		0000
		15:0	—	—	—	IC5IP<2:0>			IC5IS<1:0>		—	—	—	T5IP<2:0>			T5IS<1:0>		0000
10F0	IPC6	31:16	—	—	—	CMP1IP<2:0>			CMP1IS<1:0>		—	—	—	FCEIP<2:0>			FCEIS<1:0>		0000
		15:0	—	—	—	RTCCIP<2:0>			RTCCIS<1:0>		—	—	—	FSCMIP<2:0>			FSCMIS<1:0>		0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: With the exception of those noted, all registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

2: These bits are not available on PIC32MX1XX devices.

3: This register does not have associated CLR, SET, INV registers.

REGISTER 10-12: U1ADDR: USB ADDRESS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	LSPDEN	DEVADDR<6:0>						

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7 **LSPDEN:** Low-Speed Enable Indicator bit
1 = Next token command to be executed at Low-Speed
0 = Next token command to be executed at Full-Speed

bit 6-0 **DEVADDR<6:0>:** 7-bit USB Device Address bits

REGISTER 10-13: U1FRML: USB FRAME NUMBER LOW REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	FRML<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7-0 **FRML<7:0>:** The 11-bit Frame Number Lower bits
The register bits are updated with the current frame number whenever a SOF TOKEN is received.

TABLE 11-7: PERIPHERAL PIN SELECT OUTPUT REGISTER MAP (CONTINUED)

Virtual Address (BF80_#)	Register Name	Bit Range	Bits															All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
FB8C	RPC8R(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPC8<3:0>				0000
FB90	RPC9R(3)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPC9<3:0>				0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register is only available on 44-pin devices.
2: This register is only available on PIC32MX1XX devices.
3: This register is only available on 36-pin and 44-pin devices.

13.2 Timer Control Registers

TABLE 13-1: TIMER2-TIMER5 REGISTER MAP

Virtual Address (BF80_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
0800	T2CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	TGATE	TCKPS<2:0>			T32	—	TCS	—	0000
0810	TMR2	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	TMR2<15:0>																0000
0820	PR2	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	PR2<15:0>																FFFF
0A00	T3CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	TGATE	TCKPS<2:0>			—	—	TCS	—	0000
0A10	TMR3	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	TMR3<15:0>																0000
0A20	PR3	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	PR3<15:0>																FFFF
0C00	T4CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	TGATE	TCKPS<2:0>			T32	—	TCS	—	0000
0C10	TMR4	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	TMR4<15:0>																0000
0C20	PR4	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	PR4<15:0>																FFFF
0E00	T5CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	TGATE	TCKPS<2:0>			—	—	TCS	—	0000
0E10	TMR5	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	TMR5<15:0>																0000
0E20	PR5	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	PR5<15:0>																FFFF

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

16.1 Output Compare Control Registers

TABLE 16-1: OUTPUT COMPARE 1-OUTPUT COMPARE 5 REGISTER MAP

Virtual Address (BF80_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
3000	OC1CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3010	OC1R	31:16	OC1R<31:0>																xxxx
		15:0																	xxxx
3020	OC1RS	31:16	OC1RS<31:0>																xxxx
		15:0																	xxxx
3200	OC2CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3210	OC2R	31:16	OC2R<31:0>																xxxx
		15:0																	xxxx
3220	OC2RS	31:16	OC2RS<31:0>																xxxx
		15:0																	xxxx
3400	OC3CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3410	OC3R	31:16	OC3R<31:0>																xxxx
		15:0																	xxxx
3420	OC3RS	31:16	OC3RS<31:0>																xxxx
		15:0																	xxxx
3600	OC4CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3610	OC4R	31:16	OC4R<31:0>																xxxx
		15:0																	xxxx
3620	OC4RS	31:16	OC4RS<31:0>																xxxx
		15:0																	xxxx
3800	OC5CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3810	OC5R	31:16	OC5R<31:0>																xxxx
		15:0																	xxxx
3820	OC5RS	31:16	OC5RS<31:0>																xxxx
		15:0																	xxxx

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

21.0 REAL-TIME CLOCK AND CALENDAR (RTCC)

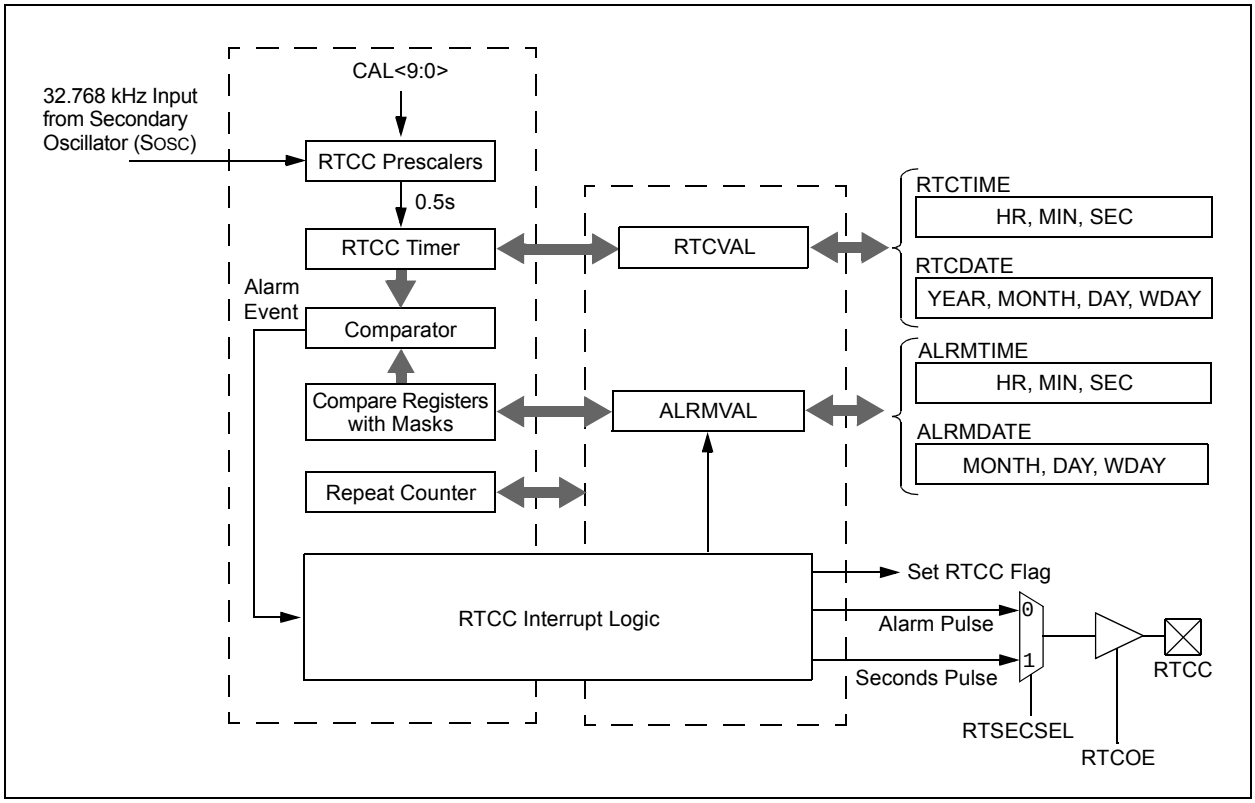
Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 29. "Real-Time Clock and Calendar (RTCC)"** (DS60001125), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The PIC32 RTCC module is intended for applications in which accurate time must be maintained for extended periods of time with minimal or no CPU intervention. Low-power optimization provides extended battery lifetime while keeping track of time.

Following are some of the key features of this module:

- Time: hours, minutes and seconds
- 24-hour format (military time)
- Visibility of one-half second period
- Provides calendar: day, date, month and year
- Alarm intervals are configurable for half of a second, one second, 10 seconds, one minute, 10 minutes, one hour, one day, one week, one month and one year
- Alarm repeat with decrementing counter
- Alarm with indefinite repeat: Chime
- Year range: 2000 to 2099
- Leap year correction
- BCD format for smaller firmware overhead
- Optimized for long-term battery operation
- Fractional second synchronization
- User calibration of the clock crystal frequency with auto-adjust
- Calibration range: ±0.66 seconds error per month
- Calibrates up to 260 ppm of crystal error
- Requirements: External 32.768 kHz clock crystal
- Alarm pulse or seconds clock output on RTCC pin

FIGURE 21-1: RTCC BLOCK DIAGRAM



25.0 CHARGE TIME MEASUREMENT UNIT (CTMU)

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 37. "Charge Time Measurement Unit (CTMU)"** (DS60001167), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

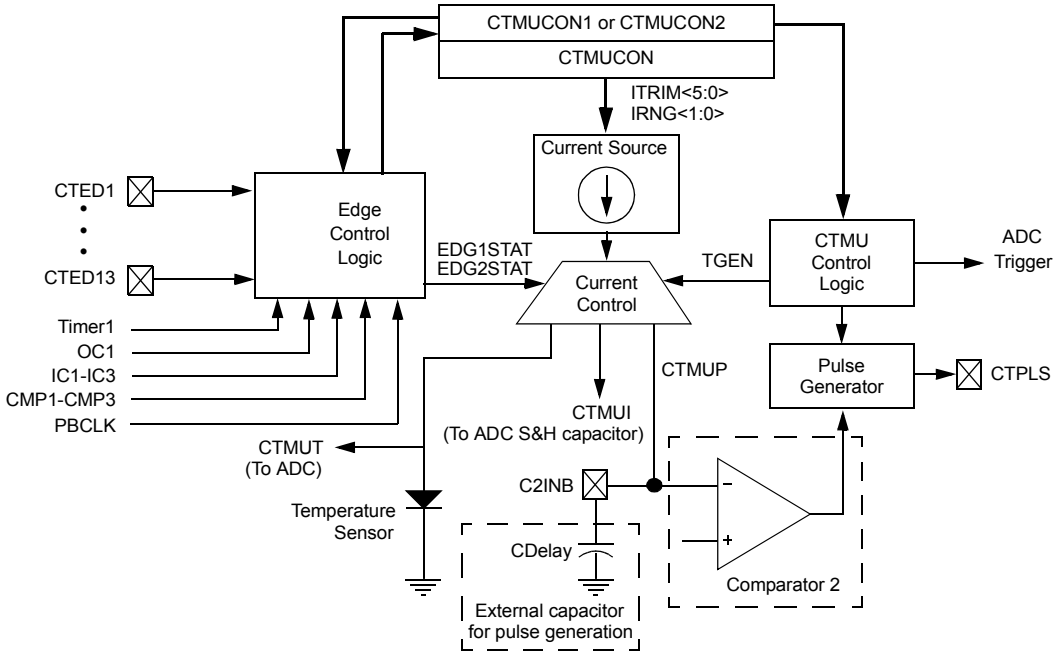
The Charge Time Measurement Unit (CTMU) is a flexible analog module that has a configurable current source with a digital configuration circuit built around it. The CTMU can be used for differential time measurement between pulse sources and can be used for generating an asynchronous pulse. By working with other on-chip analog modules, the CTMU can be used for high resolution time measurement, measure capacitance, measure relative changes in capacitance or generate output pulses with a specific time delay. The CTMU is ideal for interfacing with capacitive-based sensors.

The CTMU module includes the following key features:

- Up to 13 channels available for capacitive or time measurement input
- On-chip precision current source
- 16-edge input trigger sources
- Selection of edge or level-sensitive inputs
- Polarity control for each edge source
- Control of edge sequence
- Control of response to edges
- High precision time measurement
- Time delay of external or internal signal asynchronous to system clock
- Integrated temperature sensing diode
- Control of current source during auto-sampling
- Four current source ranges
- Time measurement resolution of one nanosecond

A block diagram of the CTMU is shown in Figure 25-1.

FIGURE 25-1: CTMU BLOCK DIAGRAM



Current Control Selection	TGEN	EDG1STAT, EDG2STAT
CTMUT	0	EDG1STAT = EDG2STAT
CTMUI	0	EDG1STAT ≠ EDG2STAT
CTMUP	1	EDG1STAT ≠ EDG2STAT
No Connect	1	EDG1STAT = EDG2STAT

25.1 CTMU Control Registers

TABLE 25-1: CTMU REGISTER MAP

Virtual Address (BF80_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
A200	CTMUCON	31:16	EDG1MOD	EDG1POL	EDG1SEL<3:0>				EDG2STAT	EDG1STAT	EDG2MOD	EDG2POL	EDG2SEL<3:0>				—	—	0000
		15:0	ON	—	CTMUSIDL	TGEN	EDGEN	EDGSEQEN	IDISSEN	CTTRIG	ITRIM<5:0>						IRNG<1:0>		0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

The processor will exit, or 'wake-up', from Sleep on one of the following events:

- On any interrupt from an enabled source that is operating in Sleep. The interrupt priority must be greater than the current CPU priority.
- On any form of device Reset
- On a WDT time-out

If the interrupt priority is lower than or equal to the current priority, the CPU will remain Halted, but the PBCLK will start running and the device will enter into Idle mode.

26.3.2 IDLE MODE

In Idle mode, the CPU is Halted but the System Clock (SYSCLK) source is still enabled. This allows peripherals to continue operation when the CPU is Halted. Peripherals can be individually configured to Halt when entering Idle by setting their respective SIDL bit. Latency, when exiting Idle mode, is very low due to the CPU oscillator source remaining active.

Note 1: Changing the PBCLK divider ratio requires recalculation of peripheral timing. For example, assume the UART is configured for 9600 baud with a PB clock ratio of 1:1 and a POSC of 8 MHz. When the PB clock divisor of 1:2 is used, the input frequency to the baud clock is cut in half; therefore, the baud rate is reduced to 1/2 its former value. Due to numeric truncation in calculations (such as the baud rate divisor), the actual baud rate may be a tiny percentage different than expected. For this reason, any timing calculation required for a peripheral should be performed with the new PB clock frequency instead of scaling the previous value based on a change in the PB divisor ratio.

2: Oscillator start-up and PLL lock delays are applied when switching to a clock source that was disabled and that uses a crystal and/or the PLL. For example, assume the clock source is switched from POSC to LPRC just prior to entering Sleep in order to save power. No oscillator start-up delay would be applied when exiting Idle. However, when switching back to POSC, the appropriate PLL and/or oscillator start-up/lock delays would be applied.

The device enters Idle mode when the SLPEN (OSCCON<4>) bit is clear and a `WAIT` instruction is executed.

The processor will wake or exit from Idle mode on the following events:

- On any interrupt event for which the interrupt source is enabled. The priority of the interrupt event must be greater than the current priority of the CPU. If the priority of the interrupt event is lower than or equal to current priority of the CPU, the CPU will remain Halted and the device will remain in Idle mode.
- On any form of device Reset
- On a WDT time-out interrupt

26.3.3 PERIPHERAL BUS SCALING METHOD

Most of the peripherals on the device are clocked using the PBCLK. The Peripheral Bus can be scaled relative to the SYSCLK to minimize the dynamic power consumed by the peripherals. The PBCLK divisor is controlled by PBDIV<1:0> (OSCCON<20:19>), allowing SYSCLK to PBCLK ratios of 1:1, 1:2, 1:4 and 1:8. All peripherals using PBCLK are affected when the divisor is changed. Peripherals such as the USB, Interrupt Controller, DMA, and the bus matrix are clocked directly from SYSCLK. As a result, they are not affected by PBCLK divisor changes.

Changing the PBCLK divisor affects:

- The CPU to peripheral access latency. The CPU has to wait for next PBCLK edge for a read to complete. In 1:8 mode, this results in a latency of one to seven SYSCLKs.
- The power consumption of the peripherals. Power consumption is directly proportional to the frequency at which the peripherals are clocked. The greater the divisor, the lower the power consumed by the peripherals.

To minimize dynamic power, the PB divisor should be chosen to run the peripherals at the lowest frequency that provides acceptable system performance. When selecting a PBCLK divider, peripheral clock requirements, such as baud rate accuracy, should be taken into account. For example, the UART peripheral may not be able to achieve all baud rate values at some PBCLK divider depending on the SYSCLK value.

26.4 Peripheral Module Disable

The Peripheral Module Disable (PMD) registers provide a method to disable a peripheral module by stopping all clock sources supplied to that module. When a peripheral is disabled using the appropriate PMD control bit, the peripheral is in a minimum power consumption state. The control and status registers associated with the peripheral are also disabled, so writes to those registers do not have effect and read values are invalid.

To disable a peripheral, the associated PMDx bit must be set to '1'. To enable a peripheral, the associated PMDx bit must be cleared (default). See Table 26-1 for more information.

Note:	Disabling a peripheral module while it's ON bit is set, may result in undefined behavior. The ON bit for the associated peripheral module must be cleared prior to disable a module via the PMDx bits.

TABLE 26-1: PERIPHERAL MODULE DISABLE BITS AND LOCATIONS

Peripheral(1)	PMDx bit Name(1)	Register Name and Bit Location
ADC1	AD1MD	PMD1<0>
CTMU	CTMUMD	PMD1<8>
Comparator Voltage Reference	CVRMD	PMD1<12>
Comparator 1	CMP1MD	PMD2<0>
Comparator 2	CMP2MD	PMD2<1>
Comparator 3	CMP3MD	PMD2<2>
Input Capture 1	IC1MD	PMD3<0>
Input Capture 2	IC2MD	PMD3<1>
Input Capture 3	IC3MD	PMD3<2>
Input Capture 4	IC4MD	PMD3<3>
Input Capture 5	IC5MD	PMD3<4>
Output Compare 1	OC1MD	PMD3<16>
Output Compare 2	OC2MD	PMD3<17>
Output Compare 3	OC3MD	PMD3<18>
Output Compare 4	OC4MD	PMD3<19>
Output Compare 5	OC5MD	PMD3<20>
Timer1	T1MD	PMD4<0>
Timer2	T2MD	PMD4<1>
Timer3	T3MD	PMD4<2>
Timer4	T4MD	PMD4<3>
Timer5	T5MD	PMD4<4>
UART1	U1MD	PMD5<0>
UART2	U2MD	PMD5<1>
SPI1	SPI1MD	PMD5<8>
SPI2	SPI2MD	PMD5<9>
I2C1	I2C1MD	PMD5<16>
I2C2	I2C2MD	PMD5<17>
USB(2)	USBMD	PMD5<24>
RTCC	RTCCMD	PMD6<0>
Reference Clock Output	REFOMD	PMD6<1>
PMP	PMPMD	PMD6<16>

Note 1: Not all modules and associated PMDx bits are available on all devices. See **TABLE 1: "PIC32MX1XX 28/36/44-Pin General Purpose Family Features"** and **TABLE 2: "PIC32MX2XX 28/36/44-pin USB Family Features"** for the lists of available peripherals.

2: The module must not be busy after clearing the associated ON bit and prior to setting the USBMD bit.

TABLE 30-12: DC CHARACTERISTICS: PROGRAM MEMORY

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical(1)**	**Max.**	**Units**	**Conditions**
		Program Flash Memory(3)					
D130	EP	Cell Endurance	20,000	—	—	E/W	—
D131	VPR	VDD for Read	2.3	—	3.6	V	—
D132	VPEW	VDD for Erase or Write	2.3	—	3.6	V	—
D134	TRETD	Characteristic Retention	20	—	—	Year	Provided no other specifications are violated
D135	IDDP	Supply Current during Programming	—	10	—	mA	—
	TWW	Word Write Cycle Time	—	411	—	FRC Cycles	See **Note 4**
D136	TRW	Row Write Cycle Time	—	6675	—		See **Note 2,4**
D137	TPE	Page Erase Cycle Time	—	20011	—		See **Note 4**
	TCE	Chip Erase Cycle Time	—	80180	—		See **Note 4**

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated.

2: The minimum SYSCLK for row programming is 4 MHz. Care should be taken to minimize bus activities during row programming, such as suspending any memory-to-memory DMA operations. If heavy bus loads are expected, selecting Bus Matrix Arbitration mode 2 (rotating priority) may be necessary. The default Arbitration mode is mode 1 (CPU has lowest priority).

3: Refer to the *"PIC32 Flash Programming Specification"* (DS60001145) for operating conditions during programming and erase cycles.

4: This parameter depends on FRC accuracy (See Table 30-19) and FRC tuning values (See Register 8-2).

TABLE 30-32: I2Cx BUS DATA TIMING REQUIREMENTS (MASTER MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp			
Param. No.	**Symbol**	**Characteristics**		**Min.(1)**	**Max.**	**Units**	**Conditions**
IM10	TLO:SCL	Clock Low Time	100 kHz mode	TPB * (BRG + 2)	—	µs	—
			400 kHz mode	TPB * (BRG + 2)	—	µs	—
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	—
IM11	THI:SCL	Clock High Time	100 kHz mode	TPB * (BRG + 2)	—	µs	—
			400 kHz mode	TPB * (BRG + 2)	—	µs	—
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	—
IM20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode **(Note 2)**	—	100	ns	
IM21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode **(Note 2)**	—	300	ns	
IM25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	—
			400 kHz mode	100	—	ns	
			1 MHz mode **(Note 2)**	100	—	ns	
IM26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	µs	—
			400 kHz mode	0	0.9	µs	
			1 MHz mode **(Note 2)**	0	0.3	µs	
IM30	TSU:STA	Start Condition Setup Time	100 kHz mode	TPB * (BRG + 2)	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	TPB * (BRG + 2)	—	µs	
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	
IM31	THD:STA	Start Condition Hold Time	100 kHz mode	TPB * (BRG + 2)	—	µs	After this period, the first clock pulse is generated
			400 kHz mode	TPB * (BRG + 2)	—	µs	
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	
IM33	TSU:STO	Stop Condition Setup Time	100 kHz mode	TPB * (BRG + 2)	—	µs	—
			400 kHz mode	TPB * (BRG + 2)	—	µs	
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	
IM34	THD:STO	Stop Condition Hold Time	100 kHz mode	TPB * (BRG + 2)	—	ns	—
			400 kHz mode	TPB * (BRG + 2)	—	ns	
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	ns	

Note 1: BRG is the value of the I^2C Baud Rate Generator.

2: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

3: The typical value for this parameter is 104 ns.

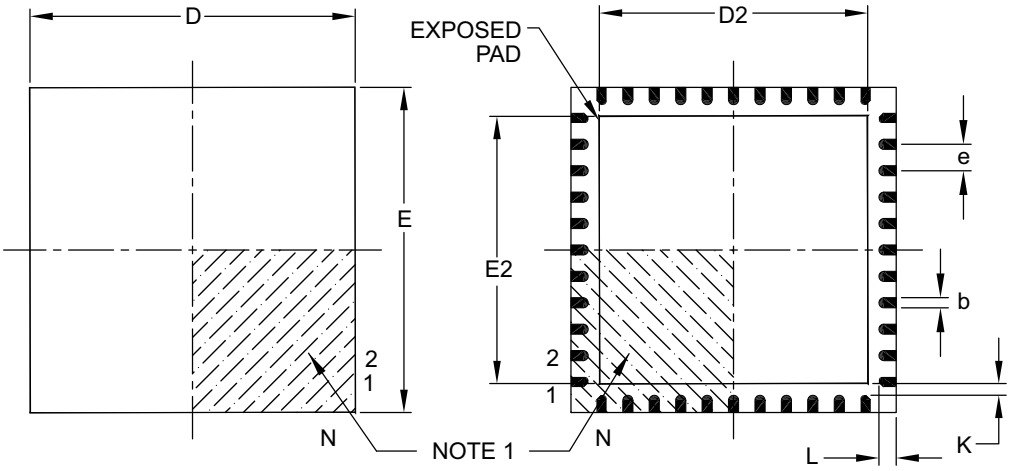
TABLE 30-33: I2Cx BUS DATA TIMING REQUIREMENTS (SLAVE MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp			
Param. No.	**Symbol**	**Characteristics**		**Min.**	**Max.**	**Units**	**Conditions**
IS10	TLO:SCL	Clock Low Time	100 kHz mode	4.7	—	μs	PBCLK must operate at a minimum of 800 kHz
			400 kHz mode	1.3	—	μs	PBCLK must operate at a minimum of 3.2 MHz
			1 MHz mode **(Note 1)**	0.5	—	μs	—
IS11	THI:SCL	Clock High Time	100 kHz mode	4.0	—	μs	PBCLK must operate at a minimum of 800 kHz
			400 kHz mode	0.6	—	μs	PBCLK must operate at a minimum of 3.2 MHz
			1 MHz mode **(Note 1)**	0.5	—	μs	—
IS20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode **(Note 1)**	—	100	ns	
IS21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode **(Note 1)**	—	300	ns	
IS25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	—
			400 kHz mode	100	—	ns	
			1 MHz mode **(Note 1)**	100	—	ns	
IS26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	ns	—
			400 kHz mode	0	0.9	μs	
			1 MHz mode **(Note 1)**	0	0.3	μs	
IS30	TSU:STA	Start Condition Setup Time	100 kHz mode	4700	—	ns	Only relevant for Repeated Start condition
			400 kHz mode	600	—	ns	
			1 MHz mode **(Note 1)**	250	—	ns	
IS31	THD:STA	Start Condition Hold Time	100 kHz mode	4000	—	ns	After this period, the first clock pulse is generated
			400 kHz mode	600	—	ns	
			1 MHz mode **(Note 1)**	250	—	ns	
IS33	TSU:STO	Stop Condition Setup Time	100 kHz mode	4000	—	ns	—
			400 kHz mode	600	—	ns	
			1 MHz mode **(Note 1)**	600	—	ns	

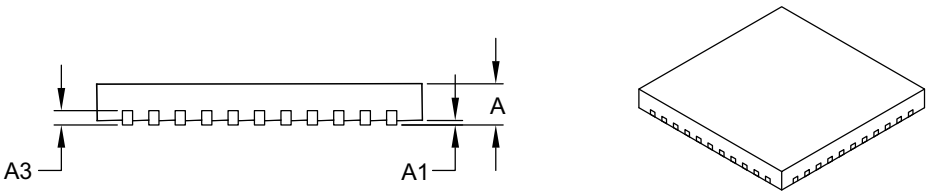
Note 1: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

44-Lead Plastic Quad Flat, No Lead Package (ML) – 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW **BOTTOM VIEW**



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		44	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Width	E		8.00 BSC	
Exposed Pad Width	E2	6.30	6.45	6.80
Overall Length	D		8.00 BSC	
Exposed Pad Length	D2	6.30	6.45	6.80
Contact Width	b	0.25	0.30	0.38
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	–	–

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-103B

TABLE A-1: MAJOR SECTION UPDATES (CONTINUED)

Section	Update Description
4.0 "Memory Organization"	Added Memory Maps for the new devices (see Figure 4-3 and Figure 4-4). Removed the BMXCHEDMA bit from the Bus Matrix Register map (see Table 4-1). Added the REFOTRIM register, added the DIVSWEN bit to the REFOCON registers, added Note 4 to the ULOCK and SOSCEN bits and added the PBDIVRDY bit in the OSCCON register in the in the System Control Register map (see Table 4-16). Removed the ALTI2C1 and ALTI2C2 bits from the DEVCFG3 register and added Note 1 to the UPLLEN and UPLLIDIV<2:0> bits of the DEVCFG2 register in the Device Configuration Word Summary (see Table 4-17). Updated Note 1 in the Device and Revision ID Summary (see Table 4-18). Added Note 2 to the PORTA Register map (see Table 4-19). Added the ANSB6 and ANSB12 bits to the ANSELB register in the PORTB Register map (see Table 4-20). Added Notes 2 and 3 to the PORTC Register map (see Table 4-21). Updated all register names in the Peripheral Pin Select Register map (see Table 4-23). Added values in support of new devices (16 KB RAM and 32 KB RAM) in the Data RAM Size register (see Register 4-5). Added values in support of new devices (64 KB Flash and 128 KB Flash) in the Data RAM Size register (see Register 4-5).
8.0 "Oscillator Configuration"	Added Note 5 to the PIC32MX1XX/2XX Family Clock Diagram (see Figure 8-1). Added the PBDIVRDY bit and Note 2 to the Oscillator Control register (see Register 8-1). Added the DIVSWEN bit and Note 3 to the Reference Oscillator Control register (see Register 8-3). Added the REFOTRIM register (see Register 8-4).
21.0 "10-bit Analog-to-Digital Converter (ADC)"	Updated the ADC1 Module Block Diagram (see Figure 21-1). Updated the Notes in the ADC Input Select register (see Register 21-4).
24.0 "Charge Time Measurement Unit (CTMU)"	Updated the CTMU Block Diagram (see Figure 24-1). Added Note 3 to the CTMU Control register (see Register 24-1)
26.0 "Special Features"	Added Note 1 and the PGEC4/PGED4 pin pair to the ICESEL<1:0> bits in DEVCFG0: Device Configuration Word 0 (see Register 26-1). Removed the ALTI2C1 and ALTI2C2 bits from the Device Configuration Word 3 register (see Register 26-4). Removed 26.3.3 "Power-up Requirements". Added Note 3 to the Connections for the On-Chip Regulator diagram (see Figure 26-2). Updated the Block Diagram of Programming, Debugging and Trace Ports diagram (see Figure 26-3).

Revision G (April 2015)

This revision includes the addition of the following devices:

- PIC32MX130F256B
- PIC32MX230F256B
- PIC32MX130F256D
- PIC32MX230F256D

The title of the document was updated to avoid confusion with the PIC32MX1XX/2XX/5XX 64/100-pin Family data sheet.

All peripheral SFR maps have been relocated from the Memory chapter to their respective peripheral chapters.

In addition, this revision includes the following major changes as described in Table A-6, as well as minor updates to text and formatting, which were incorporated throughout the document.

TABLE A-6: MAJOR SECTION UPDATES

Section	Update Description
32-bit Microcontrollers (up to 256 KB Flash and 64 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog	Added new devices to the family features (see Table 1 and Table 2). Updated pin diagrams to include new devices (see Pin Diagrams).
2.0 "Guidelines for Getting Started with 32-bit MCUs"	Updated these sections: **2.2 "Decoupling Capacitors"**, **2.3 "Capacitor on Internal Voltage Regulator (VCAP)"**, **2.4 "Master Clear (MCLR) Pin"**, **2.8.1 "Crystal Oscillator Design Consideration"**
4.0 "Memory Organization"	Added Memory Map for new devices (see Figure 4-6).
14.0 "Watchdog Timer (WDT)"	New chapter created from content previously located in the Special Features chapter.
30.0 "Electrical Characteristics"	Removed parameter D312 (TSET) from the Comparator Specifications (see Table 30-12). Added the Comparator Voltage Reference Specifications (see Table 30-13). Updated Table 30-12.

Revision H (July 2015)

This revision includes the following major changes as described in Table A-7, as well as minor updates to text and formatting, which were incorporated throughout the document.

TABLE A-7: MAJOR SECTION UPDATES

Section	Update Description
2.0 "Guidelines for Getting Started with 32-bit MCUs"	**Section 2.9 "Sosc Design Recommendation"** was removed.
8.0 "Oscillator Configuration"	The Primary Oscillator (POSC) logic in the Oscillator diagram was updated (see Figure 8-1).
30.0 "Electrical Characteristics"	The Power-Down Current (IPD) DC Characteristics parameter DC40k was updated (see Table 30-7). **Table 30-9: "DC Characteristics: I/O Pin Input Injection current Specifications"** was added.

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